Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L13	42	(leadframe or (lead near frame)) with (thermally adj (conductive or conducting) adj substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 14:00
L14	28	((leadframe or (lead near frame)) with (thermally adj (conductive or conducting) adj substrate)).ti,ab, clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 14:02
L15	6	((leadframe or (lead near frame)) with (thermally adj (conductive or conducting) adj substrate)) with plate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 14:03
L16	14	((leadframe or (lead near frame)) with (thermally adj (conductive or conducting) adj substrate)) with (heatsink or radiation or plate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 14:05
L17	4	((leadframe or (lead near frame)) with (thermally adj (conductive or conducting) adj substrate)) with (heatsink or radiation or plate) with (insulating or insulator or dielectric)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 14:06
L18	506	((leadframe or (lead near frame)) with (heatsink or radiation or plate) with (insulating or insulator or dielectric))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 14:07
L19	22	((leadframe or (lead near frame)) with (heatsink or radiation or plate) with (insulating or insulator or dielectric) with sheet)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 14:10
L20	506	((leadframe or (lead near frame)) with (heatsink or radiation or plate) with (insulating or insulator or dielectric))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 14:10
L21	42	((leadframe or (lead near frame)) with (heatsink or radiation or plate) with (insulating or insulator or dielectric)) and (thermally adj (conductive or conducting))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 14:10

L22	10	((leadframe or (lead near frame)) with (heatsink or radiation or plate) with (insulating or insulator or dielectric)).clm. and (thermally adj (conductive or conducting))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 14:11
L23	4	((leadframe or (lead near frame)) with (heatsink or radiation or plate) with (insulating or insulator or dielectric)).clm. and (thermally adj (conductive or conducting) adj substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 14:12
L24	6	((leadframe or (lead near frame)) with (heatsink or radiation or plate) with (insulating or insulator or dielectric)) and (thermally adj (conductive or conducting) adj substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 14:12
L25	756	(thermally adj (conductive or conducting) adj substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 14:13
L26	398	(thermally adj (conductive or conducting) adj substrate) and (heatsink or radiation or plate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 14:13
L27	505	(thermally adj (conductive or conducting) adj substrate) and (heatsink or radiation or plate or (heat near sink))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 14:13
L28	267	(thermally adj (conductive or conducting) adj substrate).ti,ab, clm. and (heatsink or radiation or plate or (heat near sink))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 14:14
L29	176	(thermally adj (conductive or conducting) adj substrate).ti,ab, clm. and (heatsink or radiation or plate or (heat near sink)).ti,ab, clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 14:14
L30	63	(thermally adj (conductive or conducting) adj substrate).ti,ab, clm. and (heatsink or radiation or plate or (heat near sink)).ti,ab, clm. and method.ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 14:16

| L31 | 18 | (thermally adj (conductive or conducting) adj substrate).ti,ab, clm. and (heatsink or radiation or plate or (heat near sink)).ti,ab, clm. and method.ti,ab,clm. and (lead or leadframe or (lead near frame)).ti,ab,clm. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/18 14:16 |